BRIGHTEK

BRIGHTEK (EUROPE) LIMITED

Brighten Up The World With LED !

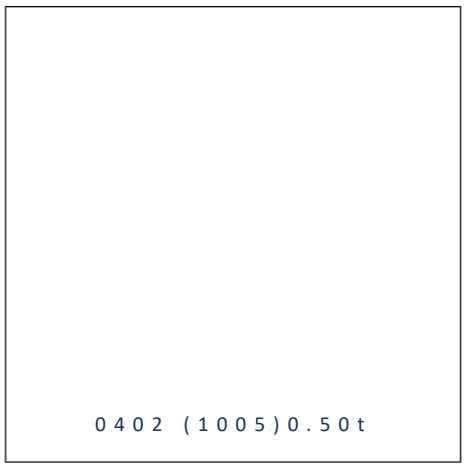
ISO/TS 16949:2009 BS EN ISO 14001:2004 QC 080000 IECQ HSPM

PRODUCT DATASHEET

- ▶ CHIP LED Top View
- ▶ 0402 (1005) 0.50t
- ▶ Red 624nm

Release Date: 22 July 2026 Version: A1.1

N0R68S92



0402 (1005) 0.50t

RoHS Compliant

FEATURES:

- **Package:** CHIP/PCB SMT Top View Package
- **Forward Current:** 20mA
- **Forward Voltage (typ.):** 2.0V
- **Luminous Intensity (typ.):** 112.5mcd@20mA
- **Colour:** Red
- **Dominant Wavelength (typ.):** 624nm
- **Viewing Angle:** X=120°; Y=128°
- **Materials:**
  - Resin: Epoxy (Water Clear)
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+100°C
- **Grouping Parameters:**
  - Forward Voltage
  - Luminous Intensity
  - Dominant Wavelength
- **Soldering Methods:** Reflow
- **MSL Level:** 2a according to J-STD020
- **Packing:** 8mm tape with max.4000pcs /reel, ø178mm (7'')

APPLICATIONS:

- Backlighting
- 3C Consumer Goods
- Indicator
- Light Strip

CHARACTERISTICS:

Absolute Maximum Characteristics (T_a=25°C)

Parameter	Symbol	Ratings	Unit
DC Forward Current	I_F	20	mA
Pulse Forward Current Duty Cycle 1/10, 1kHz	I_{PF}	100	mA
Reverse Voltage	V_R	5	V
Reverse Current @5V	I_R	10	μA
Power Dissipation	P_D	48	mW
Operating Temperature	T_{OPR}	-40~+85	°C
Storage Temperature	T_{STG}	-40~+100	°C

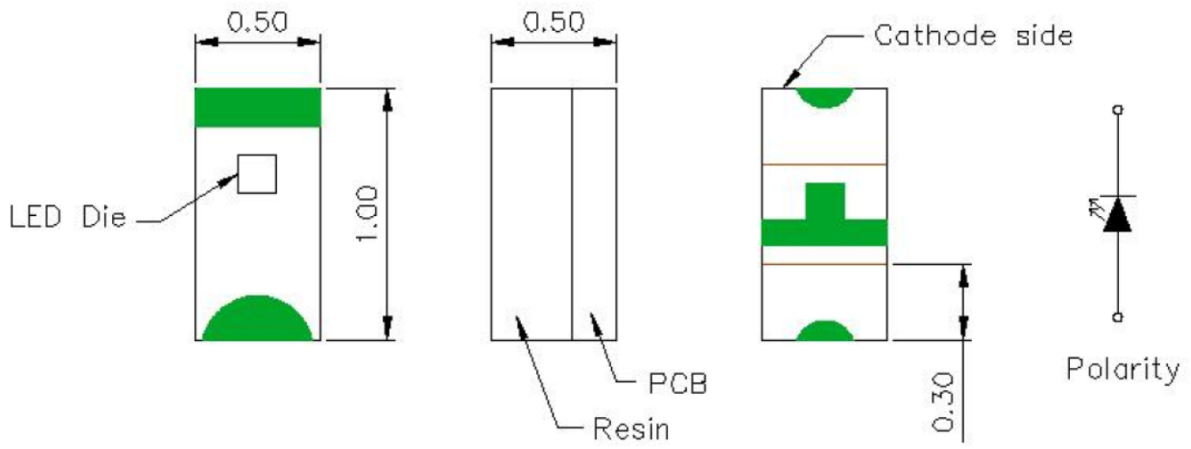
Electrical & Optical Characteristics (T_a=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V_F	---	2.0	2.4	V	I_F=20mA
Luminous Intensity	I_V	---	112.5	---	mcd	I_F=20mA
Dominant Wavelength	λ_D	---	624	---	nm	I_F=20mA
Peak Wavelength	λ_P	---	632	---	nm	I_F=20mA
Spectrum Radiation Bandwidth	$\Delta\lambda$	---	20	---	nm	I_F=20mA
Viewing Angle (X/Y)	$2\theta_{1/2}$	---	120/128	---	deg	I_F=20mA

1. Luminous intensity (I_V) ±10%, Forward Voltage (V_F) ±0.1V, Viewing angle($2\theta_{1/2}$) ±5°

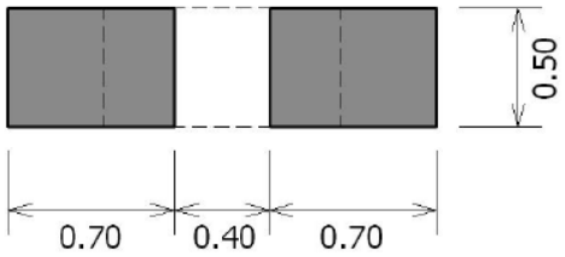
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance ±0.13mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



Recommended PCB Solder Pad

1. Dimensions are in millimetre (mm).
2. Tolerance ±0.12mm with angle tolerance ±0.5°.

BINNING GROUPS:

Forward Voltage Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
E18	1.6	2.4	V

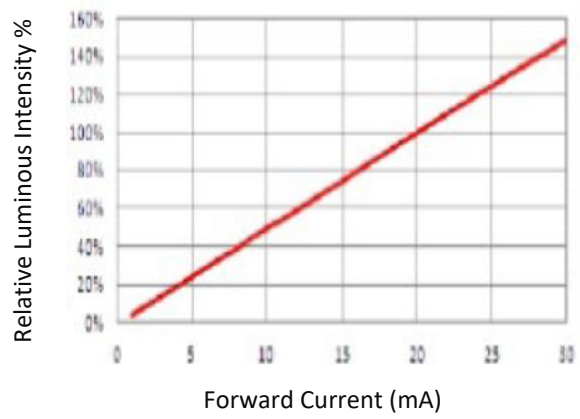
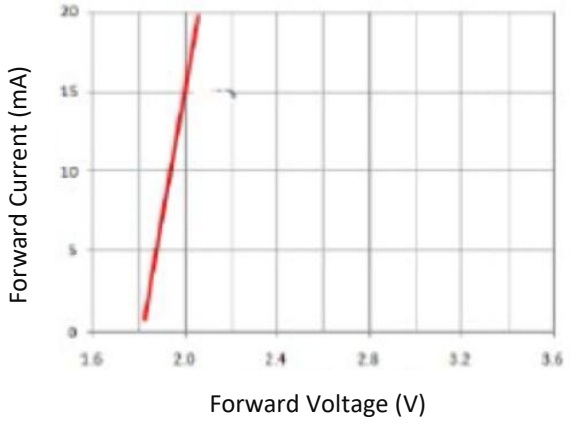
Luminous Intensity Classifications (I_F = 20mA):

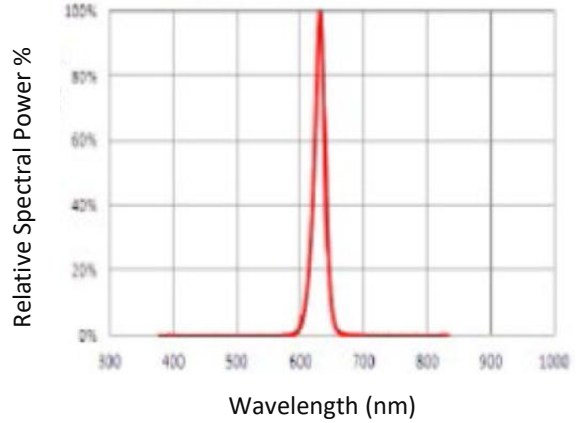
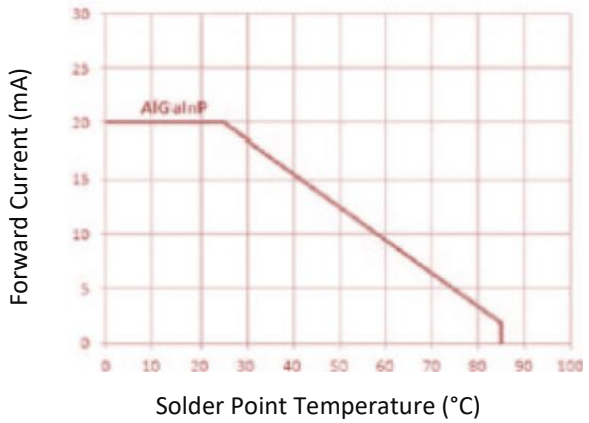
Code	Min.	Max.	Unit
P	45.0	71.5	mcd
Q	71.5	112.5	
R	112.5	180.0	
S	180.0	285.0	

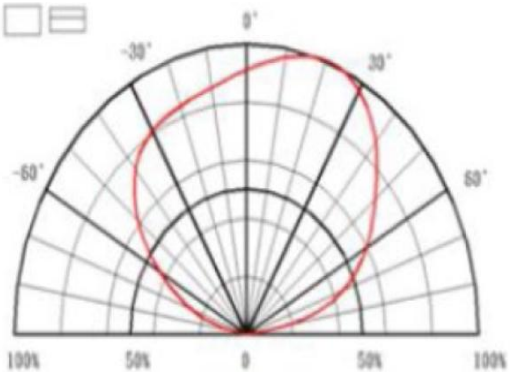
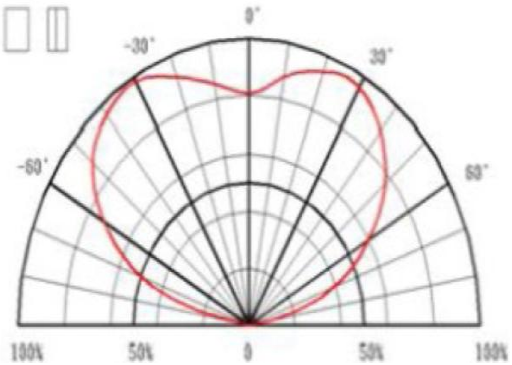
Dominant Wavelength Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
AD	615	635	nm

ELECTRO-OPTICAL CHARACTERISTICS:

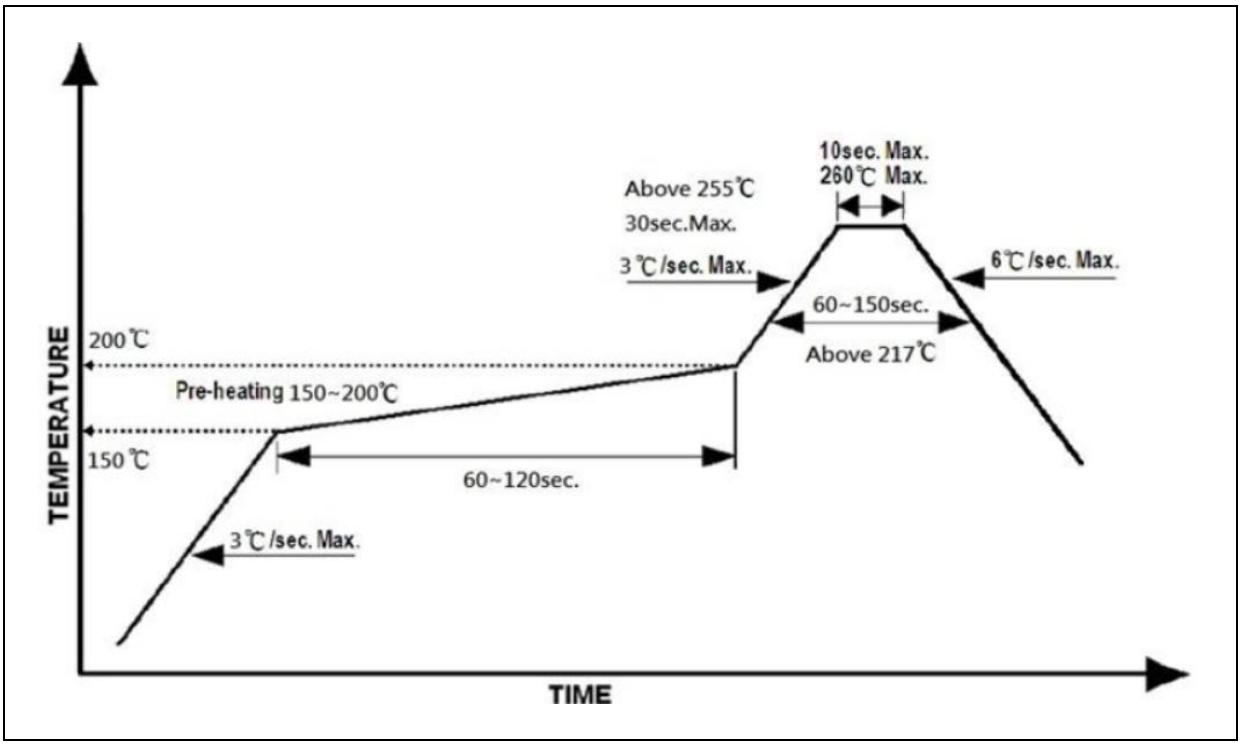
Relative Luminous Intensity vs. Forward Current	Forward Current vs. Forward Voltage
	

Relative Spectral Power vs. Wavelength	Forward Current Derating Curve
	

Directive Radiation X	Directive Radiation Y
	

RECOMMENDED SOLDERING PROFILE:

Reflow Lead-free Solder:



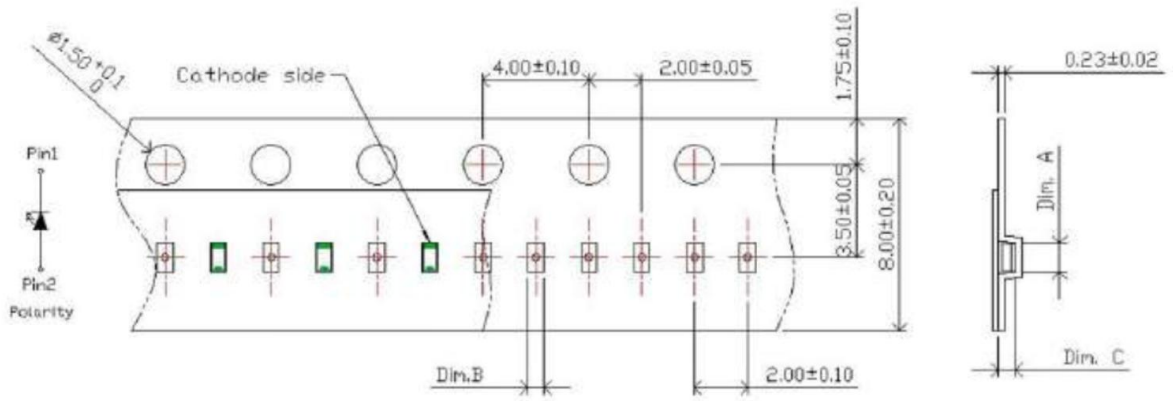
Note:

1. Maximum reflow soldering: 2 times.
2. The recommended reflow temperature is 240°C. The maximum soldering temperature should be limited to 260°C.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.

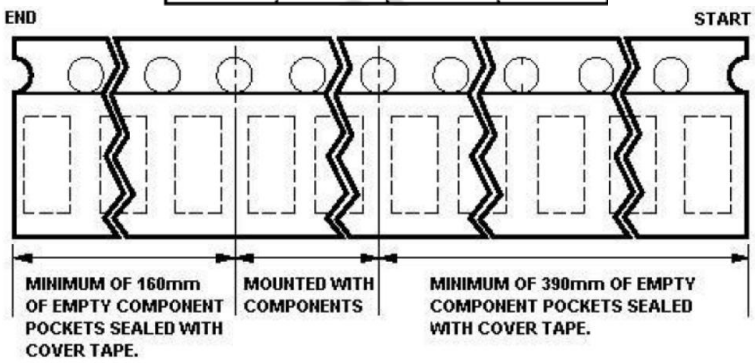
PACKING SPECIFICATION:

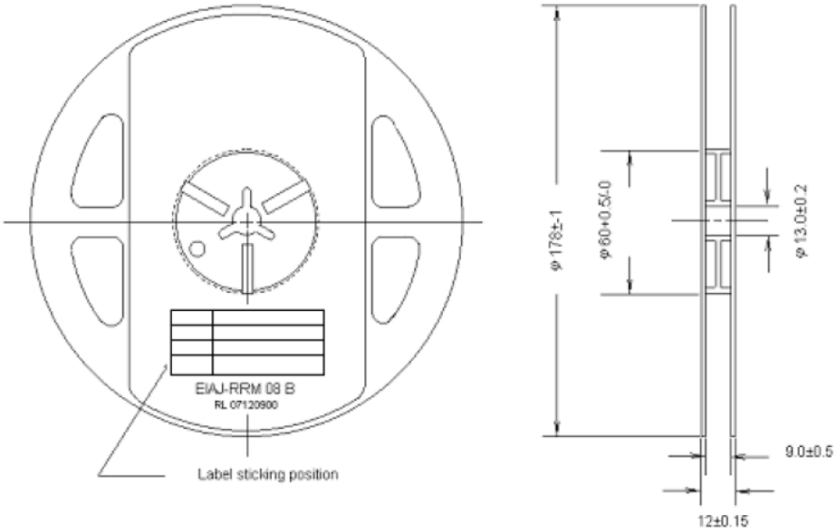
Reel Dimension:

Max.4000pcs/reel



Dim. A	Dim. B	Dim. C	Q'ty/Reel
1.1±0.05	0.60±0.05	0.66±0.05	4K





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within 4 weeks. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

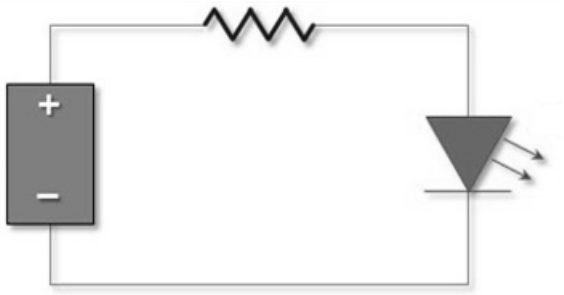
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±3°C x 12hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	25/06/2026	Datasheet set-up.
A1.1	22/07/2026	Revise pulse current value.